

IT-170GTTC

High Tg / Halogen Free/Mid Loss Laminate & Prepreg

- Halogen free, High-Tg (185°C by DSC)
- Lower Dk (3.9 @ 10GHz) and low Df (0.0095 @ 10GHz)
- Compatible with High Tg standard FR-4 processes
- Low CTE & High thermal/CAF resistance reliability

Laminate properties

Items	IPC TM-650	Typical Value	Unit
Peel Strength Low profile copper foil	2.4.8	4.0	lb/inch
Volume Resistivity	2.5.17.1	1x10 ¹⁰	MΩ-cm
Surface Resistivity	2.5.17.1	1x10 ¹⁰	MΩ
Moisture Absorption	2.6.2.1	0.10	%
Permittivity (Dk, 55% resin content) A. 1GHz B. 2GHz C. 5GHz D. 10GHz	2.5.5.13	4.0 4.0 3.9 3.9	--
Loss Tangent (Df, 55% resin content) A. 1GHz B. 2GHz C. 5GHz D. 10GHz	2.5.5.13	0.0085 0.0085 0.0085 0.0095	--
Flexural Strength A. Warp direction B. Fill direction	2.4.4	480-510 400-430	N/mm ²
Thermal Stress 10 s at 288°C A. Unetched B. Etched	2.4.13.1	Pass Pass	Rating
Flammability	UL94	N/A	Rating
Glass Transition Temperature (DSC)	2.4.25	185	°C
Decomposition Temperature (@5%wt)	2.4.24.6	380	°C
X/Y Axis CTE(40°C to 125°C)	2.4.41	11/13	ppm/°C
Z-Axis CTE A. Alpha 1 B. Alpha 2 C. 50°C to 260°C	2.4.24	45 183 2.2	ppm/°C ppm/°C %
Thermal Resistance A. T260 B. T288	2.4.24.1	>60 >60	Minutes Minutes

For pcb technical problems, ipcb knowledgeable support team is here to help you with every step.

You can also request pcb quotation here.

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